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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/865,006	05/23/2001	Krishna Parat	042390P7462D	4672
7590 04/19/2005		EXAMINER		
Michael A. Bernadicou			DIAZ, JOSE R	
BLAKELY, SO	OKOLOFF, TAYLOR	& ZAFMAN LLP		
Seventh Floor			ART UNIT	PAPER NUMBER
12400 Wilshire Boulevard			2815	
Los Angeles, CA 90025-1026			B	_

Please find below and/or attached an Office communication concerning this application or proceeding.

			5701			
	Application No	. Applicant(s)				
0.00	09/865,006	PARAT ET AL.				
Office Action Summary	Examiner	Art Unit				
	José R. Díaz	2815				
The MAILING DATE of this commun Period for Reply	ication appears on the cove	r sheet with the correspondence a	iddress			
A SHORTENED STATUTORY PERIOD F THE MAILING DATE OF THIS COMMUN - Extensions of time may be available under the provisions after SIX (6) MONTHS from the mailing date of this comm - If the period for reply specified above, the maximum st - Failure to reply within the set or extended period for reply Any reply received by the Office later than three months earned patent term adjustment. See 37 CFR 1.704(b).	ICATION. s of 37 CFR 1.136(a). In no event, how nunication. 30) days, a reply within the statutory migratutory period will apply and will expire will, by statute, cause the application	vever, may a reply be timely filed inimum of thirty (30) days will be considered time SIX (6) MONTHS from the mailing date of this to become ABANDONED (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) file	ed on 24 January 2005.					
· <u> </u>	2b)⊠ This action is non-fir	nal.				
<i>,</i> —	☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is					
closed in accordance with the pract	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims						
4) ⊠ Claim(s) 4 and 9-11 is/are pending 4a) Of the above claim(s) is/a 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 4 and 9-11 is/are rejected. 7) □ Claim(s) is/are objected to. 8) □ Claim(s) are subject to restrict	are withdrawn from conside					
Application Papers						
9)☐ The specification is objected to by th	e Examiner.		·			
10) ☐ The drawing(s) filed on is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.						
Applicant may not request that any obje	-	·				
Replacement drawing sheet(s) including 11) The oath or declaration is objected to						
Priority under 35 U.S.C. § 119						
12) Acknowledgment is made of a claim a) All b) Some * c) None of: 1. Certified copies of the priority 2. Certified copies of the priority 3. Copies of the certified copies application from the Internation * See the attached detailed Office action	documents have been rec documents have been rec of the priority documents h onal Bureau (PCT Rule 17.	eived. eived in Application No nave been received in this National ((a)).	al Stage			
Attachment(s)						
1) Notice of References Cited (PTO-892)	4)	Interview Summary (PTO-413)				
2) Notice of Draftsperson's Patent Drawing Review (I	PTO-948)	Paper No(s)/Mail Date	OTO 152)			
Information Disclosure Statement(s) (PTO-1449 or Paper No(s)/Mail Date	· · · - · · · · · · · · · · · · · · · ·	Notice of Informal Patent Application (P) Other:	10-132)			

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 2. Claim 4 is rejected under 35 U.S.C. 102(e) as being anticipated by Inoue (US Pat. No. 6,284,624 B1).

Regarding claim 4, Inoue teaches a method comprising:

forming a trench (4) in a silicon substrate (1) (see fig. 2);

growing an oxide (6) in said trench (see fig. 13);

removing all of said grown oxide (6) from said trench (see fig. 14);

growing a second oxide (23) in said trench (see fig. 15);

filling said trench with a dielectric (8) (see fig. 16);

growing a tunnel oxide (10) on said silicon substrate adjacent to said dielectric filled trench (see fig. 17);

forming a first polysilicon layer (26) on said tunnel oxide (see fig. 25);

forming an intepoly dielectric (27) on said first polysilicon layer (see fig. 25);

forming a polysilicon control gate (28) on said interpoly dielectric (see fig. 25).

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Claims 9-11 are rejected under 35 U.S.C. 102(b) as being anticipated by Teng et al. (US Pat. No. 4,890,144).

Regarding claim 4, Teng et al. teaches a method comprising:

forming a trench (18) in a semiconductor substrate (12) between a first cell and a second cell (please consider the portions of the substrate that have isolation regions 16, which are located at the right and left sides of trench (18). See fig. 4);

forming an opening in a first dielectric material (20) in the trench (please note that layer 20 was removed to exposed the bottom surface of the trench. See fig. 5 and col. 4, lined 40-41);

forming a second dielectric material (24) in the opening in the fist dielectric material (see fig. 5)

forming a shared source region (30) through the opening between the first cell and the second cell (see fig. 5);

forming sidewall spacers with the second dielectric material (24) (please note that layer 24 is patterned in figure 6 to expose the bottom surface of the trench, so that layer 24 remains only on the sidewalls of the trench).

Regarding claim 10, Teng et al. further teaches growing a thermal oxide (32) in the trench (see fig. 6).

Regarding claim 11, Teng et al. further teaches forming the second dielectric material (24) with a chemical vapor deposition (CVD) process (see col. 4, lines 40-44).

Allowable Subject Matter

3. The indicated allowability of claims 9-11 is withdrawn in view of the newly discovered reference to Teng et al. Rejections based on the newly cited reference follow.

Response to Arguments

4. Applicant's arguments with respect to claims 4 and 9-11 have been considered but are most in view of the new grounds of rejection.

Correspondence

Any inquiry concerning this communication or earlier communications from the examiner should be directed to José R. Díaz whose telephone number is (571) 272-1727. The examiner can normally be reached on Monday through Thursday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Tom Thomas can be reached on (571) 272-1664. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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JRD 4/14/05

> TOM THOMAS SUPERVISORY PATENT EXAMINER